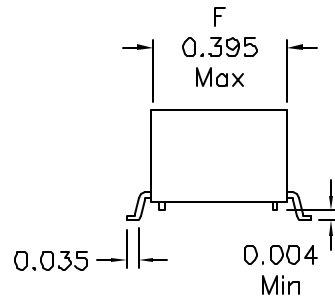
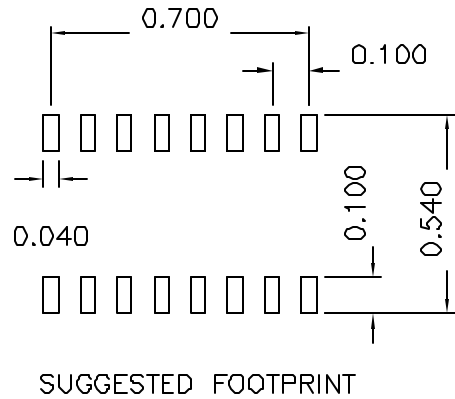
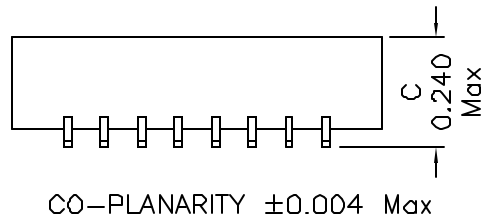
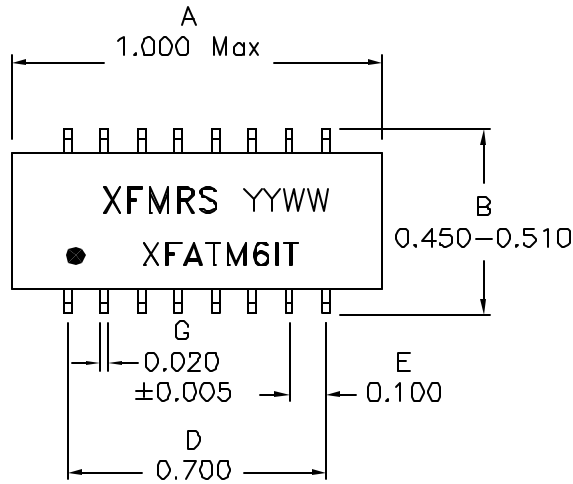


1. Mechanical Dimensions:

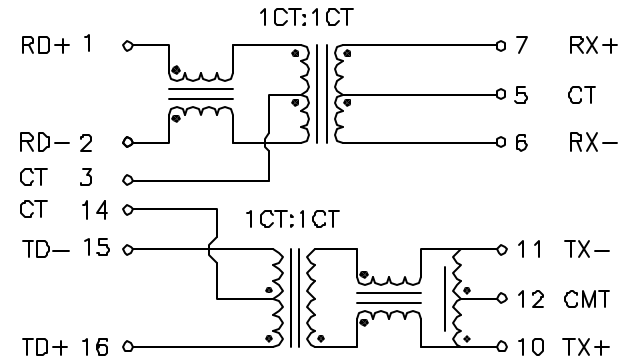


Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C, UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC REV: A/11

2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500Vrms

CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA

Rise Time (10-90%): 4.0ns Typ

Insertion Loss (100KHz-100MHz): -1.0dB Max

Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz
 -20dB -20dB -18dB -14dB (Typ)

CMRR: 30MHz 60MHz 100MHz
 -42dB -36dB -33dB (Min)

CROSSTALK: 30MHz 60MHz 100MHz
 -50dB -40dB -40dB (Min)

XFMRS Inc.		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch	P/N: XFATM6IT		REV A
	DWN.	Juan Mao	Oct-05-04
	CHK.	YK Liao	Oct-05-04
SCALE 2:1 SHT 1 OF 1	APP.	Joe Huff	Oct-05-04

PROPRIETARY

Document is the property of XFMRS Group & is not allowed to be duplicated without authorization.